


MATERIAL DECLARATION SHEET



Package Type	PTVS20-015C-TH			
Product Line	Semiconductor Products			
Compliance Date	1 st May 2022			
RoHS Compliant	Yes	MSL	Not Applicable	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Electrodes	Copper Alloy	1.6901	Copper	7440-50-8	97.000	53.683	55.032
				Zinc	7440-66-6	2.815	1.242	
				Lead	7439-92-1	0.100	0.071	
				Iron	7439-89-6	0.070	0.034	
				Phosphorus	7723-14-0	0.015	0.002	
2	Terminations	Copper Alloy	0.5652	Copper	7440-50-8	99.500	18.312	18.404
				Others	-	0.500	0.092	
3	Termination Finish	Silver	0.0036	Silver	7440-22-4	100.000	0.116	0.116
4	Encapsulation	Epoxy resin	0.5201	Bisphenol Epoxy resin	1675-54-3	39.900	4.768	16.934
				Epoxy Resin	25085-99-8	23.800	2.773	
				Crystal Silica	14464-46-1	23.000	5.956	
				Brominated Epoxy Resin	40039-93-8	9.800	1.757	
				Iron Oxide	51274-00-1	2.000	1.044	
				Titanium Oxide	13463-67-7	1.500	0.636	
5	Chip	Silicon	0.1121	Silicon	7440-21-3	89.536	3.267	3.649
				Aluminum	7429-90-5	8.244	0.301	
				Titanium	7440-32-6	0.573	0.021	
				Nickel	7440-02-0	0.977	0.036	
				Silver	7440-22-4	0.670	0.024	
6	Die Coating	Silicone	0.1032	Filler	Trade Secret	61.110	2.144	3.361
				Polysiloxane	Trade Secret	22.110	0.283	
				Fumed Silica	112945-52-5	11.110	0.542	
				Chromium Sesquioxide	1308-38-9	5.670	0.392	
7	Solder paste	Solder	0.0769	Lead*	7439-92-1	92.500	2.362	2.504
				Tin	7440-31-5	5.000	0.081	
				Silver	7440-22-4	2.500	0.061	
		Total weight	3.0712					

* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)